

Product Change Notification - KSRA-30MKCM076

Date: 12 Feb 2018

Product Category:

Notification subject: CCB 3269 Initial Notice: Qualification of 8600 die attach and G700LTD mold compound for selected products available in 8L TDFN package at NSEB assembly site.

Notification text: **PCN Status:**
Initial notification

PCN Type:
Manufacturing Change

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of 8600 die attach and G700LTD mold compound for selected products available in 8L TDFN package at NSEB assembly site.

Pre Change:

Using 8200T die attach material and G770HCD molding compound material

Post Change:

Using 8200T or 8600 die attach material and G770HCD or G700LTD molding compound material

Pre and Post Change Summary:

	Pre Change	Post Change	
Assembly Site	UTAC Thai Limited LTD. / NSEB	UTAC Thai Limited LTD. / NSEB	UTAC Thai Limited LTD. / NSEB
Wire material	Au wire	Au wire	Au wire
Die attach material	8200T	8200T	8600
Molding compound material	G770HCD	G770HCD	G700LTD
Lead frame material	C194	C194	C194

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve manufacturability by qualifying G700LTD mold compound and 8600 die attach material.

Change Implementation Status:

In Progress

Estimated Qualification Completion Date:

May 2018

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

Workweek	February 2018					→	May 2018				
	05	06	07	08	09		18	19	20	21	22
Initial PCN Issue Date			X								
Qual Report Availability							X				
Final PCN Issue Date							X				

Method to Identify Change:

Traceability code

Qualification Plan:

Please open the attachments included with this PCN labeled as PCN_#_Qual Plan

Revision History:

February 12, 2018: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

- [PCN_KSRA-30MKCM076_Affected CPN.pdf](#)
- [PCN_KSRA-30MKCM076_Qual Plan.pdf](#)
- [PCN_KSRA-30MKCM076_Affected CPN.xlsx](#)

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

PCN_KSRA-30MKCM076
CATALOG_PART_NBR
24AA00T-I/MNY
24AA128T-I/MNY
24AA256T-E/MNY
24AA256T-I/MNY
24C00T-E/MNY
24C00T-I/MNY
24FC128T-I/MNY
24FC256T-I/MNY
24LC00T-I/MNY
24LC128T-E/MNY
24LC128T-I/MNY
24LC256T-E/MNY
24LC256T-I/MNY
MCP14A0153T-E/MNY
MCP14A0154T-E/MNY
MCP14A0155T-E/MNY
MCP14A0601T-E/MNY
MCP14A0602T-E/MNY
MCP16251T-I/MNY
MCP16252T-I/MNY
MCP16311T-E/MNY
MCP16312T-E/MNY
MCP16331T-E/MNY
MCP1661T-E/MNY
MCP1662T-E/MNY
MCP1663T-E/MNY
MCP1664T-E/MNY
MCP2542FDT-E/MNY
MCP2542FDT-H/MNY
MCP2542WFDT-E/MNY
MCP2542WFDT-H/MNY
MCP2544FDT-E/MNY
MCP2544FDT-H/MNY
MCP2544WFDT-E/MNY
MCP2544WFDT-H/MNY
MCP2557FDT-H/MNY
MCP2558FDT-H/MNY
MCP621T-E/MNY
MCP631T-E/MNY
MCP651T-E/MNY
MCP661T-E/MNY
MCP6H01T-E/MNY
MCP6H02T-E/MNY

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Affected Catalog Part Numbers (CPN)

PCN_KSRA-30MKCM076
CATALOG_PART_NBR
MCP6H71T-E/MNY
MCP6H81T-E/MNY
MCP6H82T-E/MNY
MCP6H91T-E/MNY
MCP6H92T-E/MNY
MCP6V01T-E/MNY
MCP6V03T-E/MNY
MCP6V06T-E/MNY
MCP6V08T-E/MNY
MCP6V26T-E/MNY
MCP6V28T-E/MNY